

SOT1190-2

plastic low profile fine-pitch ball grid array package; 144 balls
8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA144
Package type industry code	LFBGA144
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	30-12-2010

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		9.9	-	10	10.1	mm
E	package width		9.9	-	10	10.1	mm
A	seated height		1.4	-	1.55	1.65	mm
A ₂	package height		1.1	-	1.2	1.25	mm
e	nominal pitch		-	-	0.8	-	mm
n ₂	actual quantity of termination		-	-	144	-	



2. Package outline

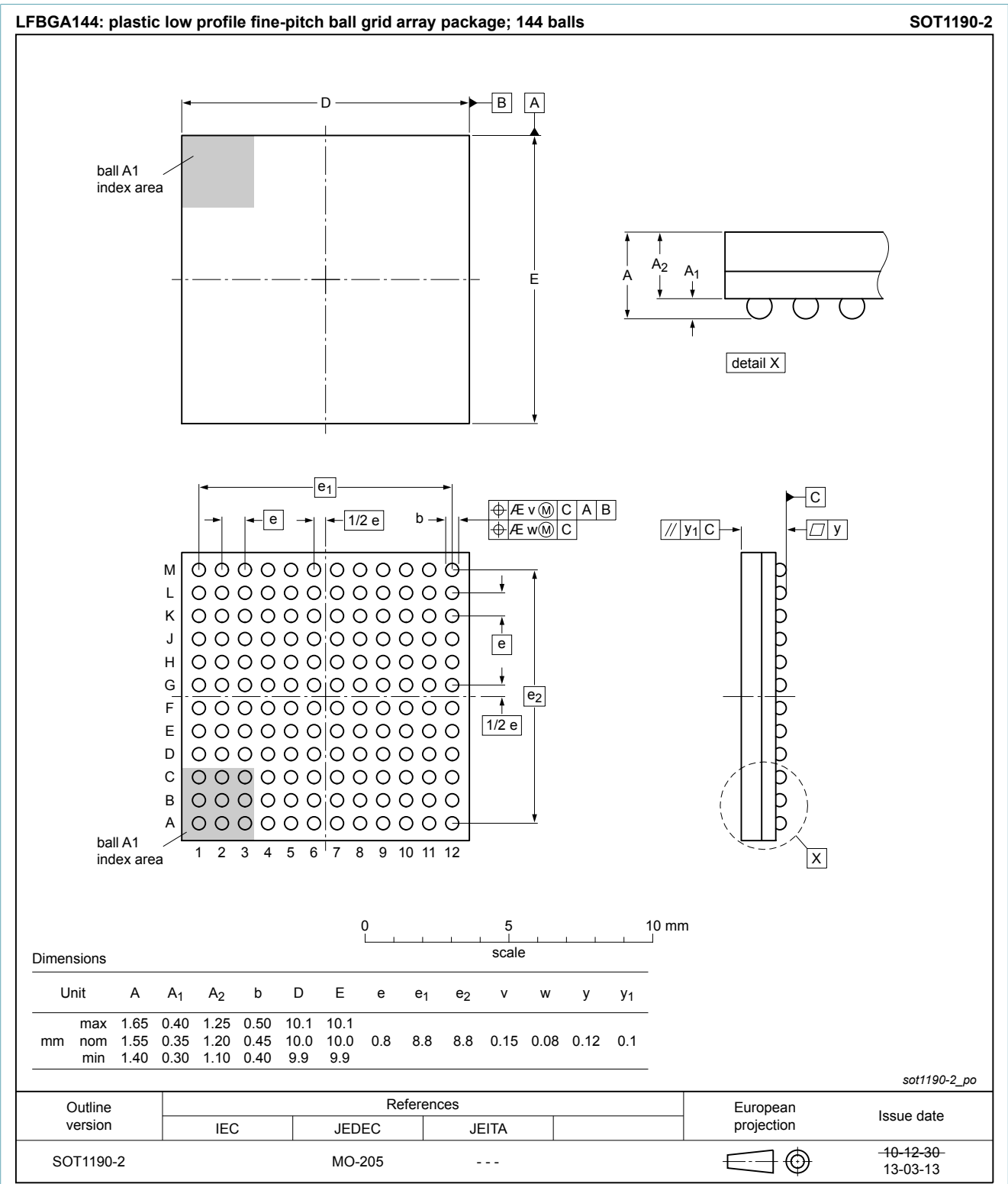


Fig. 1. Package outline LFBGA144 (SOT1190-2)

3. Legal information

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